

Description

The 5PB12xx is a high-performance TCXO/LVCMOS clock fanout buffer family with individual OE pin for each output. The CLKIN pin can accept either a square wave (LVCMOS) or clipped sine wave (such as TCXO clipped sine wave output) as input.

There are 3 different fan-out versions available: 1:3, 1:4 and 1:6.

The 5PB12xx has industry-leading low jitter and extremely low current consumption, making it ideal for smart mobile devices.

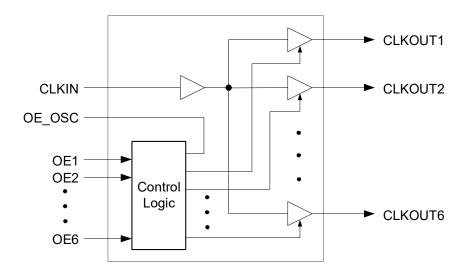
Typical Applications

- Smart Mobile Handsets
- RF and baseband peripheral clock distribution
- Automotive

Features

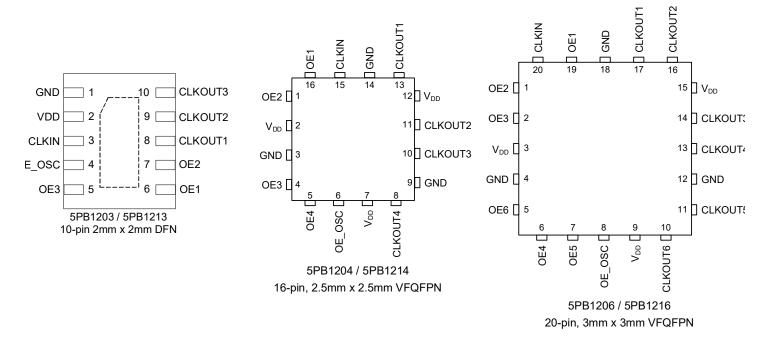
- Extremely low operating and standby current consumption
- · Low RMS additive phase jitter
- Family supports 1.8V to 3.3V power supply voltage:
 - For 1.8V supply: 5PB1203, 5PB1204, 5PB1206
 - For 2.5V / 3.3V supply: 5PB1213, 5PB1214, 5PB1216
- Three, four, and six outputs with individual Output Enable pin
- One input
- OE_OSC control pin to enable/disable reference TCXO/XO
- Small 10-pin, 16-pin and 20-pin packages available
- Industrial -40° to +105°C temperature range

Block Diagram





Pin Assignments



Pin Descriptions

		Pin Numbe	r		
Pin Name	5PB1203 5PB1213	5PB1204 5PB1214	5PB1206 5PB1216	Pin Type	Pin Description
VDD	2	2, 7, 12	3, 9, 15	Power	Connect 1.8V to 5PB1203/5PB1204/5PB1206. Connect 2.5V or 3.3V to 5PB1213/5PB1214/5PB1216.
GND	1	3, 9, 14	4, 12, 18	Power	Power supply ground.
CLKIN	3	15	20	Input	Single-ended clock input. Typically connected to a single-ended clock output.
OE_OSC	4	6	8	Output	Status pin to indicate that all OE pins are low (all outputs disabled). This pin may be used to disable an external oscillator when all outputs are disabled. Refer to Enable Function Truth Table for additional details. 0 = All OE pins indicate disabled (off) 1 = At least one OE pin indicates enabled (on)
OE1	6	16	19	Input	Output Enable pin for CLKOUT1. Active High. Internal 120kΩ pull-down.
OE2	7	1	1	Input	Output Enable pin for CLKOUT2. Active High. Internal 120kΩ pull-down.
OE3	5	4	2	Input	Output Enable pin for CLKOUT3. Active High. Internal 120kΩ pull-down.
OE4	_	5	6	Input	Output Enable pin for CLKOUT4. Active High. Internal 120kΩ pull-down.
OE5	_	_	7	Input	Output Enable pin for CLKOUT5. Active High. Internal 120kΩ pull-down.
OE6	_	_	5	Input	Output Enable pin for CLKOUT6. Active High. Internal 120kΩ pull-down.
CLKOUT1	8	13	17	Output	Clock Output 1. Same frequency as CLKIN.
CLKOUT2	9	11	16	Output	Clock Output 2. Same frequency as CLKIN.
CLKOUT3	10	10	14	Output	Clock Output 3. Same frequency as CLKIN.
CLKOUT4		8	13	Output	Clock Output 4. Same frequency as CLKIN.
CLKOUT5	_	_	11	Output	Clock Output 5. Same frequency as CLKIN.
CLKOUT6		_	10	Output	Clock Output 6. Same frequency as CLKIN.



Enable Function Truth Table

		Inj	out			Output						
OE1	OE2	OE3	OE4	OE5	OE6	OE_OSC	CLKOUT1	CLKOUT2	CLKOUT3	CLKOUT4	CLKOUT5	CLKOUT6
0	0	0	0	0	0	0	Hi-Z	Hi-Z	Hi-Z	Hi-Z	Hi-Z	Hi-Z
1	0	0	0	0	0	1	CLOCK	Hi-Z	Hi-Z	Hi-Z	Hi-Z	Hi-Z
1	1	0	0	0	0	1	CLOCK	CLOCK	Hi-Z	Hi-Z	Hi-Z	Hi-Z
1	1	1	1	1	1	1	CLOCK	CLOCK	CLOCK	CLOCK	CLOCK	CLOCK

External Components

A minimum number of external components are required for proper operation. A $0.01\mu\text{F}$ bypass capacitor should be used on each VDD pin. Use a separate ground via to the board ground plane for the capacitor. Use a separate ground via for each GND pin. Do not share the ground via. Route power from the via to the VDD plane through the bypass capacitor and then to the VDD pin. A 33Ω series termination resistor should be used on each clock output pin.

To achieve the low output skew that the 5PB12xx is capable of, careful attention must be paid to board layout. Essentially, all four outputs must have identical terminations, identical loads and identical trace geometries. If they do not, the output skew will be degraded. For example, using a 30Ω series termination on one output (with 33Ω on the others) will cause at least 15ps of skew.

Absolute Maximum Ratings

Stresses above the ratings listed below can cause permanent damage to the 5PB12xx. These ratings, which are standard values for IDT commercially rated parts, are stress ratings only. Functional operation of the device at these or any other conditions above those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods can affect product reliability. Electrical parameters are guaranteed only over the recommended operating temperature range.

Item	Rating
Supply Voltage, VDD	3.8V
Output Enable and All Inputs/Outputs	-0.5 V to VDD + 0.5 V
Ambient Operating Temperature (extended)	-40 to +105°C
Storage Temperature	-65 to +150°C
Junction Temperature	125°C
Soldering Temperature	260°C



DC Electrical Characteristics

(VDD = 1.8V, 2.5V, 3.3V)

VDD = 1.8V \pm 5\%, for **5PB1203** / **1204** / **1206**, ambient temperature -40° to +105°C, unless stated otherwise.

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Units
Operating Voltage	VDD		1.71		1.89	V
Input High Voltage, CLKIN	V _{IH}	LVCMOS input. Note 1	VDD/2 + 200		VDD	mV
Input Low Voltage, CLKIN	V _{IL}	LVCMOS input. Note 1			VDD/2 - 200	mV
Input High Voltage, OE	V _{IH}		0.7xVDD		VDD	V
Input Low Voltage, OE	V _{IL}				0.3xVDD	V
Output High Voltage	V _{OH}	I _{OH} = -4mA	0.8xVDD			V
Output Low Voltage	V _{OL}	I _{OL} = 4mA			0.2xVDD	V
Nominal Output Impedance	Z _O			17		Ω
Input Capacitance	C _{IN}			5		pF
Operating Supply Current						
5PB1203		CLKIN = 26MHz, all outputs enabled		4.76	5.91	
3PB1203		CLKIN = Low or High, all outputs disabled		0.01	0.01	
EDD4204	IDD	CLKIN = 26MHz, all outputs enabled		5.99	7.22	- A
5PB1204	טטו	CLKIN = Low or High, all outputs disabled		0.01	0.01	mA
EDD1206	1	CLKIN = 26MHz, all outputs enabled		9.15	11.39	
5PB1206		CLKIN = Low or High, all outputs disabled		0.01	0.01	

VDD = 2.5V \pm5%, for **5PB1213** / **1214** / **1216**, ambient temperature -40° to +105°C, unless stated otherwise.

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Units
Operating Voltage	VDD		2.375		2.625	V
Input High Voltage, CLKIN	V _{IH}	LVCMOS input. Note 1	VDD/2 + 200		VDD	mV
Input Low Voltage, CLKIN	V _{IL}	LVCMOS input. Note 1			VDD/2 - 200	mV
Input High Voltage, OE	V _{IH}		0.7xVDD		VDD	V
Input Low Voltage, OE	V _{IL}				0.3xVDD	V
Output High Voltage	V _{OH}	I _{OH} = -4mA	0.8xVDD			V
Output Low Voltage	V _{OL}	I _{OL} = 4mA			0.2xVDD	V
Nominal Output Impedance	Z _O			17		Ω
Input Capacitance	C _{IN}	ICLK, OE pin		5		pF
Operating Supply Current						
5PB1213		CLKIN = 26MHz, all outputs enabled		6.66	8.54	
JPB1213		CLKIN = Low or High, all outputs disabled		0.01	0.02	
5PB1214	IDD	CLKIN = 26MHz, all outputs enabled		8.36	10.48	mA
DPB1214	טטו	CLKIN = Low or High, all outputs disabled		0.01	0.03	IIIA
5PB1216		CLKIN = 26MHz, all outputs enabled		12.58	16.30	
JFD1Z10		CLKIN = Low or High, all outputs disabled		0.01	0.04	



VDD = 3.3V \pm5%, for **5PB1213 / 1214 / 1216**, ambient temperature -40° to +105°C, unless stated otherwise

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Units
Operating Voltage	VDD		3.135		3.465	V
Input High Voltage, CLKIN	V _{IH}	LVCMOS input. Note 1	VDD/2 + 200		VDD	mV
Input Low Voltage, CLKIN	V_{IL}	LVCMOS input. Note 1			VDD/2 - 200	mV
Input High Voltage, OE	V _{IH}		0.7xVDD		VDD	V
Input Low Voltage, OE	V_{IL}				0.3xVDD	V
Output High Voltage	V _{OH}	I _{OH} = -4mA	0.8xVDD			V
Output Low Voltage	V _{OL}	I _{OL} = 4mA			0.2xVDD	V
Nominal Output Impedance	Z _O			17		Ω
Input Capacitance	C _{IN}	ICLK, OE pin		5		pF
Operating Supply Current	1				-1	
5PB1213		CLKIN = 26MHz, all outputs enabled		8.96	11.65	
3PD1213		CLKIN = Low or High, all outputs disabled		0.14	0.45	
EDD4044	IDD	CLKIN = 26MHz, all outputs enabled		11.34	14.06	A
5PB1214	IDD	CLKIN = Low or High, all outputs disabled		0.20	0.63	mA
5PB1216		CLKIN = 26MHz, all outputs enabled		16.87	21.72	
10MD1210		CLKIN = Low or High, all outputs disabled		0.22	0.70	1

Notes: 1. Nominal switching threshold is VDD/2.



AC Electrical Characteristics

(VDD = 1.8V, 2.5V, 3.3V)

VDD = 1.8V ±5%; for 5PB1203 / 1204 / 1206, ambient Temperature -40° to +105°C, unless stated otherwise

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Units
Input Frequency			0		200	MHz
Output Rise Time	t _{OR}	0.36 to 1.44V, C _L = 5pF		0.6	1.0	ns
Output Fall Time	t _{OF}	1.44 to 0.36V, C _L = 5pF		0.6	1.0	ns
Propagation Delay	Note 1	Note 1	1.5	2.0	2.5	ns
Buffer Additive Phase Jitter, RMS		26MHz TCXO clipped sine wave input, Integration Range: 12kHz to 20MHz		420		fs
		125MHz LVCMOS input, Integration Range: 12kHz to 20MHz		42		fs
Output to Output Skew	t _{SKEWO-O}	Note 2, Rising edges at VDD/2		20	50	ps
Device to Device Skew	t _{SKEWD-D}	Rising edges at VDD/2			200	ps
Output Enable/Disable time (OEx to CLKOUTx driven/Hi-Z)	t _{EN/} t _{DIS}	CL < 5pF			5.5	ns
Start-up Time	t _{START-UP}				2	ms
TCXO Clock Clipped Sine Wave Input Voltage Swing Level	VIN _{pp}	VDD = 1.8V, should connect to CLKIN through AC coupling and bias circuit		0.8		V

VDD = 2.5V \pm 5\%; for **5PB1213** / **1214** / **1216**, ambient Temperature -40° to +105°C, unless stated otherwise

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Units
Input Frequency			0		200	MHz
Output Rise Time	t _{OR}	0.5 to 2.0V, C _L = 5pF		0.6	1.0	ns
Output Fall Time	t _{OF}	2.0 to 0.5V, C _L = 5pF		0.6	1.0	ns
Propagation Delay	Note 1	Note 1	1.7	2.2	2.7	ns
Buffer Additive Phase Jitter, RMS		26MHz TCXO clipped sine wave input, Integration Range: 12kHz to 20MHz		280		fs
		125MHz LVCMOS input, Integration Range: 12kHz to 20MHz		30		fs
Output to Output Skew	t _{SKEWO-O}	Note 2, Rising edges at VDD/2		20	50	ps
Device to Device Skew	t _{SKEWD-D}	Rising edges at VDD/2			200	ps
Output Enable/Disable time (OEx to CLKOUTx driven/Hi-Z)	t _{EN/} t _{DIS}	CL < 5pF			3.8	ns
Start-up Time	t _{START-UP}	Part start-up time for valid outputs after VDD ramp-up			2	ms
TCXO Clock Clipped Sine Wave Input Voltage Swing Level	VIN _{pp}	VDD = 2.5V, should connect to CLKIN through AC coupling and bias circuit		0.8		V



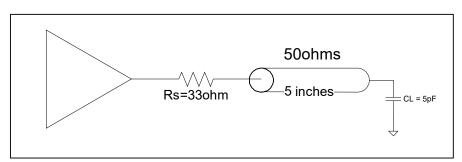
VDD = 3.3V \pm 5\%; for **5PB1213** / **1214** / **1216**, ambient Temperature -40° to +105°C, unless stated otherwise

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Units
Input Frequency			0		200	MHz
Output Rise Time	t _{OR}	0.66 to 2.64V, C _L = 5pF		0.6	1.0	ns
Output Fall Time	t _{OF}	2.64 to 0.66V, C _L = 5pF		0.6	1.0	ns
Propagation Delay	Note 1	Note 1	1.4	1.9	2.4	ns
Buffer Additive Phase Jitter, RMS		26MHz TCXO clipped sine wave input, Integration Range: 12kHz to 20MHz		377		fs
		125MHz LVCMOS input, Integration Range: 12kHz to 20MHz		18		fs
Output to Output Skew	t _{SKEWO-O}	Note 2, Rising edges at VDD/2		20	50	ps
Device to Device Skew	t _{SKEWD-D}	Rising edges at VDD/2			200	ps
Output Enable/Disable time (OEx to CLKOUTx driven/Hi-Z)	t _{EN/} t _{DIS}	CL < 5pF			3.2	ns
Start-up Time	t _{START-UP}	Part start-up time for valid outputs after VDD ramp-up			2	ms
TCXO Clock Clipped Sine Wave Input Voltage Swing Level	VIN _{pp}	VDD = 3.3V, should connect to CLKIN through AC coupling and bias circuit		0.5		V

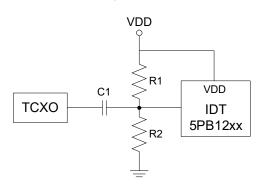
Notes:

- 1. With rail to rail input clock.
 - 2. Between any 2 outputs with equal loading.
 - 3. Duty cycle on outputs will match incoming clock duty cycle. Consult IDT for tight duty cycle clock generators.

Test Load and Circuit



AC Coupling and Bias Circuit



Component	Value
C1	0.1µF
R1	10k
R2	10k



Package Outline Drawings

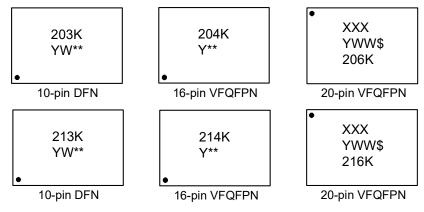
The package outline drawings are located at the end of this document and are accessible from the Renesas website (see Ordering Information for POD links). The package information is the most current data available and is subject to change without revision of this document.

Ordering Information

Part Number	Carrier	Package Description	Temp. Range
5PB1203NTGK	Cut Tape	10-pin DFN	-40 to +105°C
5PB1203NTGK8	Tape and Reel	10-pin DFN	-40 to +105°C
5PB1213NTGK	Cut Tape	10-pin DFN	-40 to +105°C
5PB1213NTGK8	Tape and Reel	10-pin DFN	-40 to +105°C
5PB1204CMGK	Cut Tape	16-pin VFQFPN	-40 to +105°C
5PB1204CMGK8	Tape and Reel	16-pin VFQFPN	-40 to +105°C
5PB1214CMGK	Cut Tape	16-pin VFQFPN	-40 to +105°C
5PB1214CMGK8	Tape and Reel	16-pin VFQFPN	-40 to +105°C
5PB1206NDGK	Tube	20-pin VFQFPN	-40 to +105°C
5PB1206NDGK8	Tape and Reel	20-pin VFQFPN	-40 to +105°C
5PB1216NDGK	Tube	20-pin VFQFPN	-40 to +105°C
5PB1216NDGK8	Tape and Reel	20-pin VFQFPN	-40 to +105°C

[&]quot;G" after the two-letter package code denotes Pb-Free configuration, RoHS compliant.

Marking Diagrams



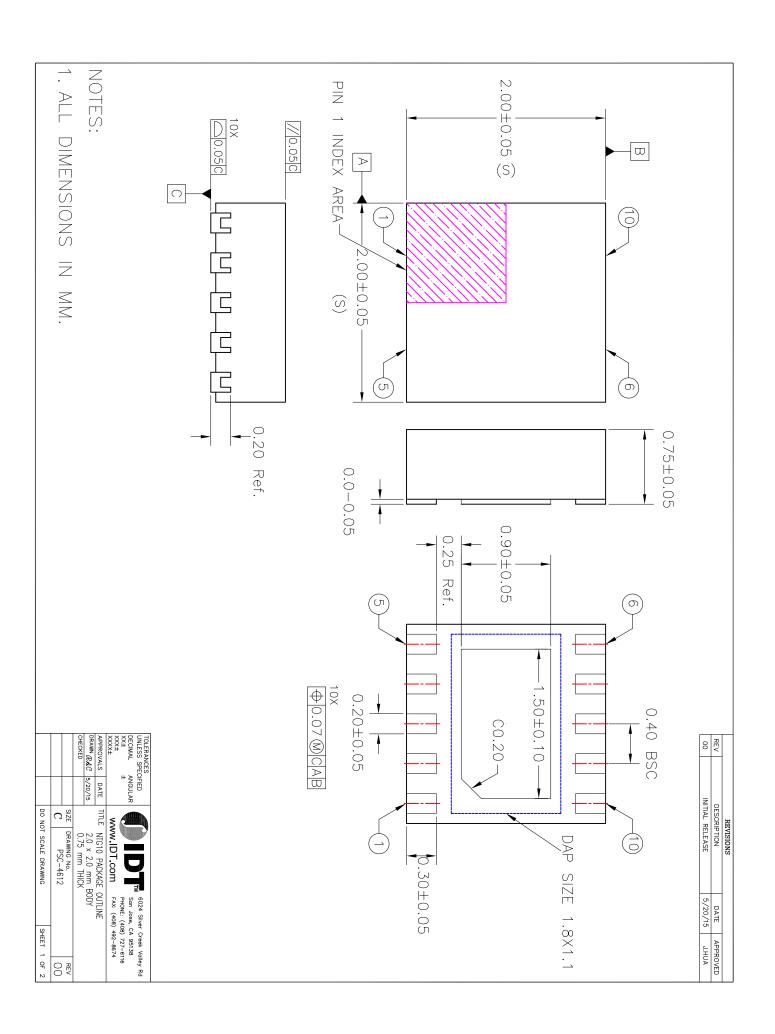
Notes:

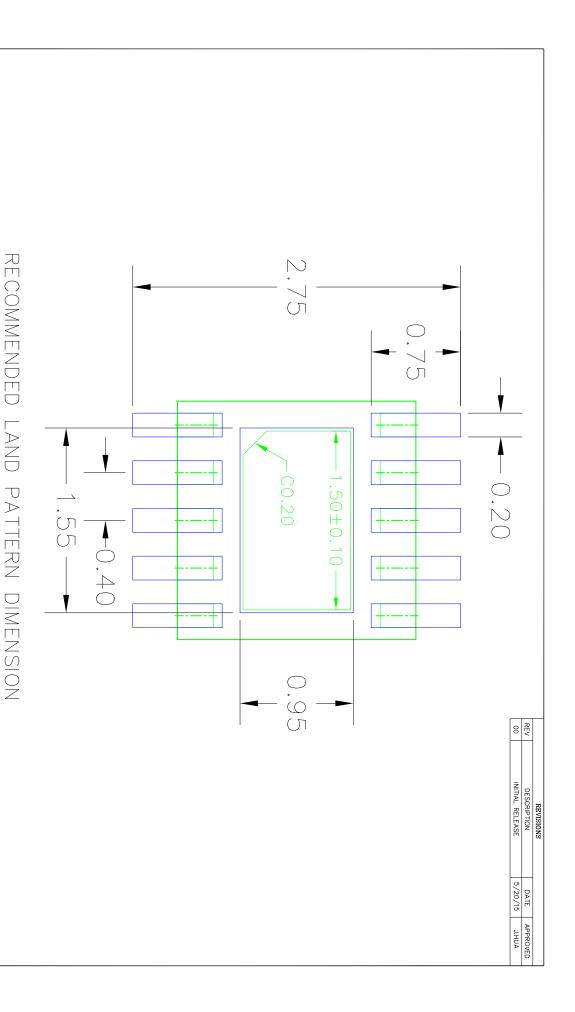
- 1. "**" is the lot number.
- 2. "YWW", "YW", or "Y" are the last digit(s) of the year and week that the part was assembled.
- 3. "\$" denotes mark location code.
- 4. "K" denotes extended temperature range device.
- 5. "XXX" denotes last three characters of Asm lot.



Revision History

Date	Description of Change
June 7, 2022	 Updated pin 1 dot location for 20-pin VFQFPN Marking Diagrams. Updated Package Outline Drawings and Ordering Information section.
December 7, 2021	 Updated Pin Descriptions. Corrected Output Enable/Disable time (OEx to CLKOUTx driven/Hi-Z) enable/disable time for 1.8V, 2.5V, and 3.3V AC Electrical Characteristics.
January 15, 2021	Updated 1st paragraph text in External Components section.
February 3, 2020	Updated the capacitor value for C1 in AC Coupling and Bias Circuit
November 22, 2019	 Updated "Operating Supply Current" data in DC Electrical Characteristics for VDD = 1.8V ±5%, VDD = 2.5V ±5%, and VDD = 3.3V ±5% Updated Package Outline Drawings; however, no mechanical changes
February 28, 2018	 Updated CLKIN input high and low voltage ratings in DC characterization tables. Updated Absolute Maximum supply voltage (VDD) from 3.465V to 3.8V.
April 10, 2017	 Updated Operating Supply Current and Operating Voltage values in DC electrical characteristics tables. Updated Propagation Delay and Output skew values in AC electrical characteristics tables. Updated package outline drawings. Updated legal disclaimer.
July 11, 2016	Initial release.





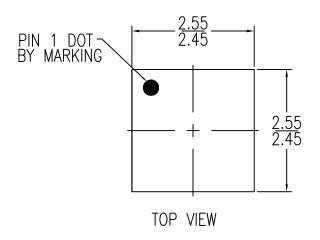
- . ALL DIMENSIONS ARE IN mm. ANGLES IN DEGREES.
 2. TOP DOWN VIEW, AS VIEWED ON PCB.
 3. COMPONENT OUTLINE IS SHOWN FOR REFERENCE IN GREEN.
 4. LAND PATTERN IN BLUE. NSMD PATTERN ASSUMED.
 5. LAND PATTERN RECOMMENDATION PER IPC-7351B GENERIC REQUIREMENT FOR SURFACE MOUNT DESIGN AND LAND PATTERN.

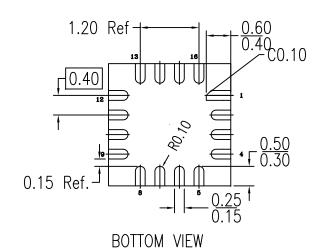
WW.IDT.com NTG10 PACKAGE C 2.0 × 2.0 mm BC 0.75 mm THICK DRAWING No. DRAWING No.			CHECKED	DRAWN RAC 5/20/15	APPROVALS DATE	CXX#	×+	DECIMAL ANGULAR	JNLESS SPECIFIED
W.IDT.com FAX: (408) 492–6874 WIGTO PACKAGE OUTLINE 2.0 × 2.0 mm BODY 0.75 mm THICK DRAWING No. PSC-4612	С	SIZE			IIIE	\$	4		
COCAT SIME CIERY FUND Son Jose, CA 951388 Son Jose, CA 951388 PHONE: (408) 727-6116 FAX: (408) 492-8674 JUTLINE	PSC-4612	DRAWING No.	0.75 mm THICK	2.0 x 2.0 mm BC	NTG10 PACKAGE C				
				DDY	UTLINE	FAX: (408) 492-8674	PHONE: (408) 727-61	San Jose, CA 95138	6024 Silver Creek Valley Rd
New Y	00	REV					16		illey Rd

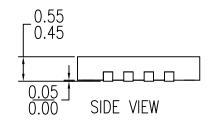
DO NOT SCALE DRAWING

SHEET 2 OF 2

REVISIONS				
DATE CREATED	REV	DESCRIPTION	AUTHOR	
4/3/14	00	INITIAL RELEASE	JH	
12/11/14	01	ADD PIN1 CHAMFER	JH	
4/5/18	02	CHANGE QFN TO VFQFPN, RECALCULATE LAND PATTERN	RC	
NOE, REFER TO DOD FOR OFFICIAL RELEASE DATE				







NOTES:

- 1. ALL DIMENSIONING AND TOLERANCING CONFORM TO ANSI Y14.5M-1982
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.

TOLERANCES UNLESS SPECIFIED DECIMAL ANGULAR X± ±1° XX± XXX±	*	6024 Silver San Jose Cr PHONE: (408) FAX: (408)	A 95138 B) 284–8200	•
DRAWN	TITLE	CMG16 Package Outline 2.5 x 2.5 x 0.5 mm E 0.40mm Pitch VFQFPN		
	SIZE	DRAWING No. PSC-4478	2	REV 02
		1 30-4470	ر	02
	DO NO	T SCALE DRAWING	SHEET 1	OF 2

REVISIONS			
DATE CREATED	REV	DESCRIPTION	AUTHOR
4/3/14	00	INITIAL RELEASE	JH
12/11/14	01	ADD PIN1 CHAMFER	JH
4/5/18	02	CHANGE QFN TO VFQFPN, RECALCULATE LAND PATTERN	RC
NOF: REFER	TO D	CP FOR OFFICIAL RELEASE DATE	

2.80 0.65 0.65 0.20 0.20 0.20 0.55

RECOMMENDED LAND PATTERN DIMENSION

NOTES:

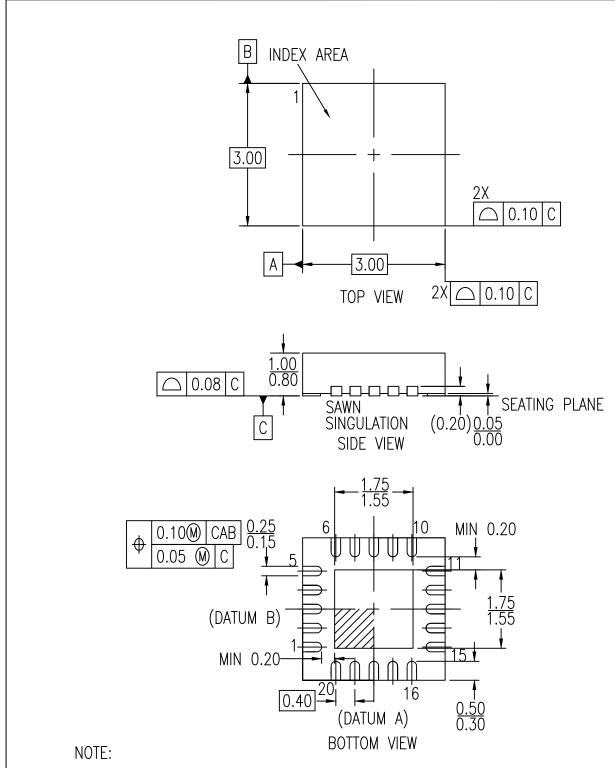
- 1. ALL DIMENSIONS ARE IN MM. ANGLES IN DEGREES.
- 2. TOP DOWN VIEW AS VIEWED ON PCB.
- 3. LAND PATTERN RECOMMENDATION PER IPC-7351B GENERIC REQUIREMENT FOR SURFACE MOUNT DESIGN AND LAND PATTERN.

TOLERANCES UNLESS SPECIFIED DECIMAL ANGULAR X± ±1° XX± XXX±	6024 Silver Creek Valley San Jose CA 95138 PHONE: (408) 284–8200 FAX: (408) 284–8591		
DRAWN	TITLE CMG16 Package Outline Drawing 2.5 x 2.5 x 0.5 mm Body 0.40mm Pitch VFQFPN		
	SIZE DRAWING No.	REV	
	C PSC-4478	02	
	DO NOT SCALE DRAWING SHEET 2	OF 2	



20-VFQFPN Package Outline Drawing

3.0 x 3.0 x 0.90 mm, 0.40mm Pitch, 1.65 x 1.65 mm Epad NDG20P2, PSC-4179-02, Rev 01, Page 1

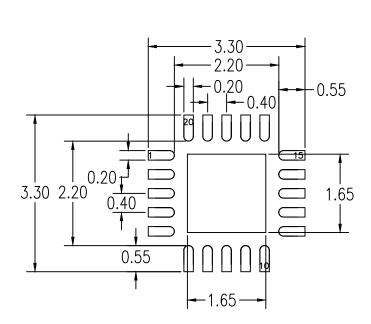


- 1. ALL DIMENSIONS ARE IN MM.
- 2. ALL DIMENSIONIONG AND TOLERANCING CONFORFM TOASME Y14.5-2009
- 3. PIN 1 LOCATION IDENTIFIER IS EITHER BY CHAMFER OR NOTCH



20-VFQFPN Package Outline Drawing

3.0 x 3.0 x 0.90 mm, 0.40mm Pitch, 1.65 x 1.65 mm Epad NDG20P2, PSC-4179-02, Rev 01, Page 2



RECOMMENDED LAND PATTERN DIMENSION

NOTES:

- 1. ALL DIMENSIONS ARE IN MM. ANGLES IN DEGREES.
- 2. TOP DOWN VIEW. AS VIEWED ON PCB.
- 3. LAND PATTERN RECOMMENDATION PER IPC-7351B GENERIC REQUIREMENT FOR SURFACE MOUNT DESIGN AND LAND PATTERN.

Package Revision History				
Date Created	Rev No.	Description		
Sept 13, 2018	Rev 01	Change QFN to VFQFPN		
Mar 30, 2016	Rev 00	Initial Release		

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(Rev.1.0 Mar 2020)

Corporate Headquarters

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